## MACOM Demonstrates Open Eye MSA Compliant Analog Chipset at CIOE 2019

September 5, 2019

- Analog chipset features a four-channel transmit CDR with integrated laser driver, quad TIA and a four-channel CDR on the receive side
- MACOM's Open Eye MSA compliant analog chipset is interoperable with multiple vendors and enables 200G (4 x 53Gbps) QSFP modules
- MACOM will host live demonstrations of the chipset enabled module at CIOE 2019 in the MACOM booth #1A32

SHENZHEN, China--(BUSINESS WIRE)--Sep. 5, 2019-- MACOM Technology Solutions Inc. ("MACOM"), a leading supplier of semiconductor solutions, today announced a live demonstration of a complete 200G optical module solution designed in collaboration with an industry leading optical manufacturer, leveraging MACOM's Open Eye MSA compliant analog chipset. The chipset is optimized for volume-scale deployment in high-density Cloud Data Center links.

This press release features multimedia. View the full release here: https://www.businesswire.com/news/home/20190905005090/en/



Targeted for faster, power efficient and lower cost optical interconnects, the chipset aims to provide a clear pathway to 200G throughput speeds utilizing industry leading analog components. MACOM's fully analog transmit and receive chipset is comprised of the MAOM-38053 four-channel transmit CDR with integrated laser driver and, on the receive side, features MACOM BSP56B photodetectors, a MATA-03819 quad TIA and the MASC-38040 four-channel receive CDR. (Photo: Business Wire)

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MACOM is applying its expertise and market leadership in 25Gbps and 100Gbps solutions to 50Gbps PAM-4 applications and specifically to 200G QSFP and 2 x

200G OSFP/QSFP-DD modules to bring the benefits of low power and low latency solutions in addition to existing digital signal processing (DSP) architectures, to Cloud Data Centers.

All of the MACOM analog chipset products mentioned in this release are Open Eye MSA compliant and interoperable with multiple vendors. MACOM's chipset is sampling to customers today and can be utilized for both single mode and multimode fiber applications. CIOE 2019 attendees are invited to visit with MACOM's booth #1A32 to preview the live demonstration and learn more about the chipset.

## ABOUT MACOM:

MACOM designs and manufactures semiconductor products for Data Center, Telecommunication and Industrial and Defense applications. Headquartered in Lowell, Massachusetts, MACOM has design centers and sales offices throughout North America, Europe and Asia. MACOM is certified to the ISO9001 international quality standard and ISO14001 environmental management standard.

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